

SPECIFICATION OF INFRARED LED CHIP

C950-40P

[INFRARED]

1) Commodity Type and Physical Characteristics.

- | | | | |
|----------------------|-------------|-------------------|------------|
| 1. Material | GaAlAs/GaAs | | |
| 2. Electrode | Top Side | P (anode)side | : Au Alloy |
| | Bottom Side | N (cathode)side | : Au Alloy |
| 3. Electrode Pattern | Fig.1 | | |
| 4. Chip Size | Fig.2 | | |
| 5. Chip Thickness | Fig.2 | | |
| 6. Emission Area | Fig.2 | | |

2) Electro-Optical Characteristics

parameters	symbol	condition	min.	typ.	max.	unit
Forward Voltage	V _f	I _f =20mA		1.25	1.35	V
Reverse Current	I _r	V _r =5V			10	μA
Power Intensity	P _o	I _f =20mA	2.0	3.5		mW
Peak Wavelength	λ _p	I _f =20mA	935	950	965	nm
Spectral Radiation Bandwidth	Δλ	I _f =20mA		50		nm
RiseTime	t _r	I _f =20mA		1000		ns
FallTime	t _f	I _f =20mA		500		ns

‡Die shall be mounted on TO-18 gold header without resin coated.(Ta=25°C)

[Unit : μm]

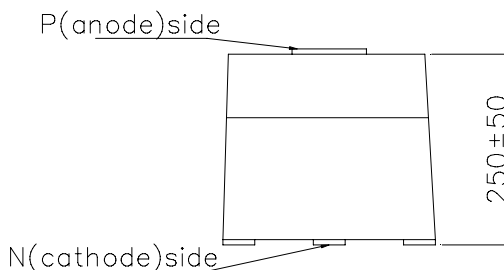
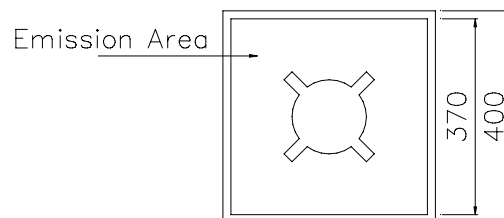
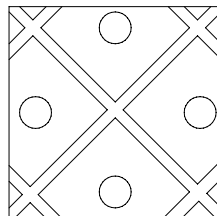
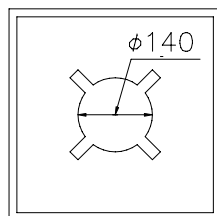


Fig.1 Electrode Pattern

Fig.2 Chip size and Emission Area

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